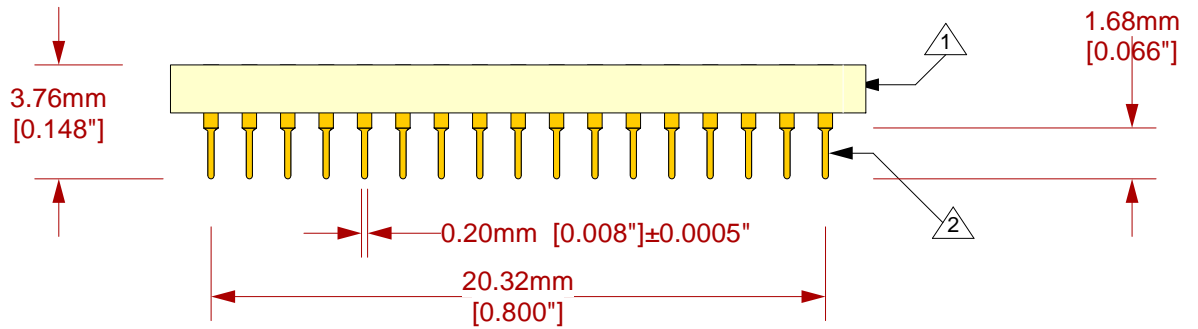


Side View




1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"]  
FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket

208 position BGA surface mount land pattern to terminal pins (1.27mm [0.050"] centers, 17x17 array)

**Tolerances:** diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	<b>LS-BGA208A-31 Drawing</b> © 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale: 4:1	Rev: A
		Drawing: S.Natarajan	Date: 5/31/05	
		File: LS-BGA208A-31 Dwg	Modified:	